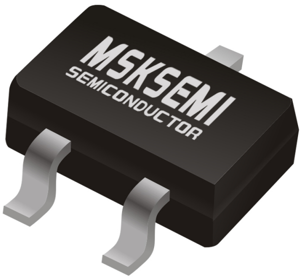
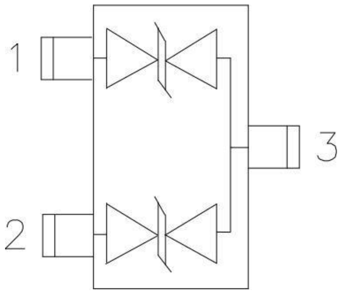


SOT-23

Pin Configuration



Features

- Ultra low leakage: nA level
- Operating voltage: 24V
- Low clamping voltage
- Complies with following standards:
  – IEC 61000-4-2 (ESD) immunity test
    Air discharge: ±30kV
    Contact discharge: ±30kV
  – IEC61000-4-4 (EFT) 40A (5/50ns)
  – IEC61000-4-5 (Lightning) 5A (8/20μs)
- RoHS Compliant
- AEC−Q101 Compliant

Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

Mechanical Characteristics

- Package: SOT-23
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7inch

Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	**Symbol**	**Value**	**Unit**
Peak Pulse Power (8/20μs)	Ppp	300	W
ESD per IEC 61000−4−2 (Air)	V_{ESD}	±30	Kv
ESD per IEC 61000−4−2 (Contact)		±30	
Operating Temperature Range	T_J	-55 to +125	℃
Storage Temperature Range	T_{STJ}	-55 to +150	℃

Electrical Characteristics(TA=25°C unless otherwise specified)

P/N	V_{RWM} (V)	V_{BR} (V)	I_T (mA)	V_C @1A	Vc		I_R µA (Max)	C (Pf) (Typ.)
					(Max)	(@A)		
PESD1CAN	24	27	1	40	45	5	0.2	25

Characteristic Curves

Fig1. 8/20µ sPulse Waveform

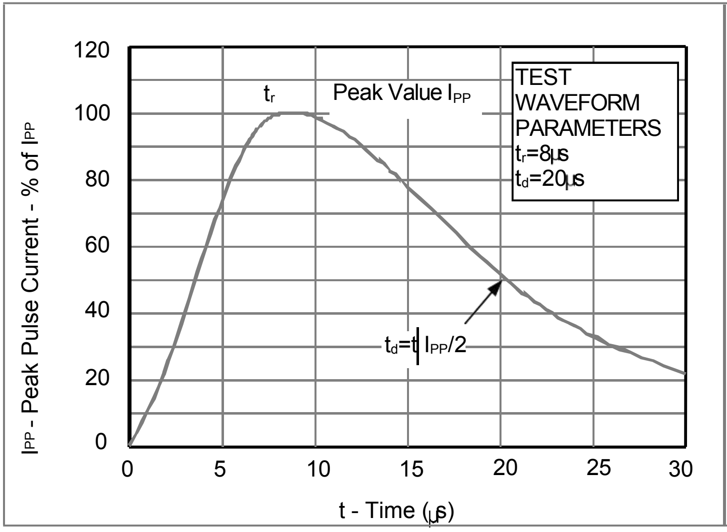


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

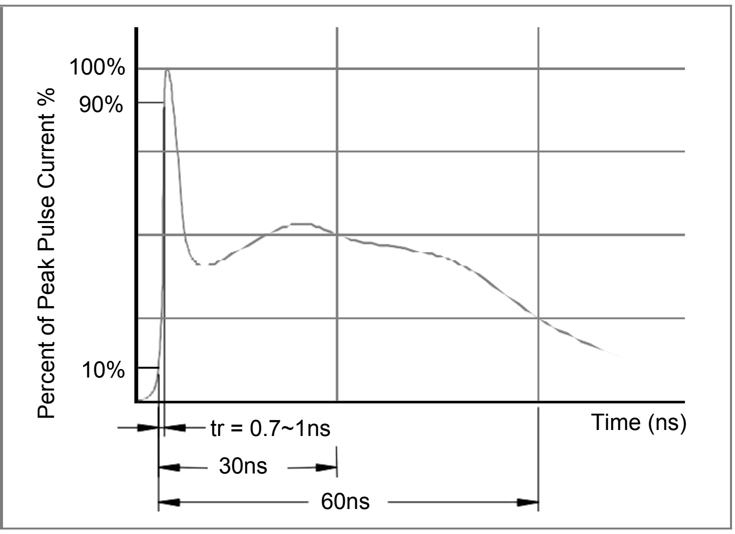
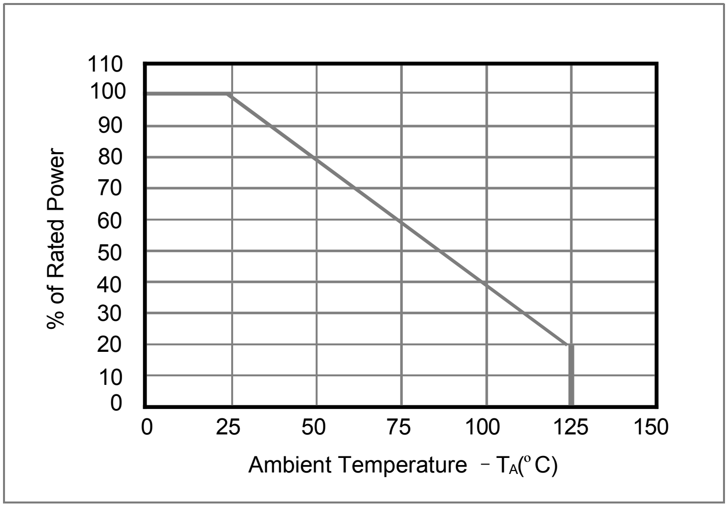
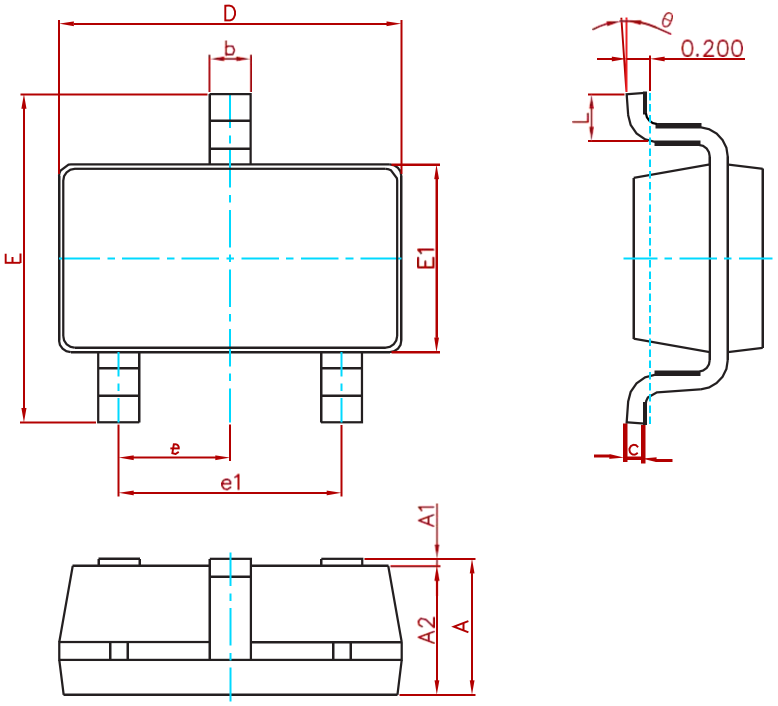


Fig3. Power Derating Curve

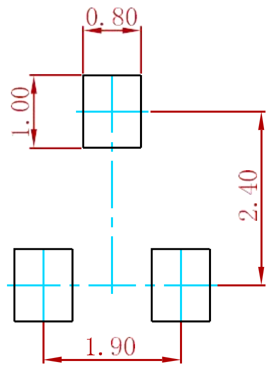


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
0	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PESD1CAN	SOT-23	3000

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